

WHAT IS CLAIMED IS:

- 5 1. A stocker comprising:
a first sealing member;
atmosphere control means for controlling an
internal atmosphere of said first sealing member to a
first atmosphere; and
transfer means for transporting an object to be
stocked to an exposure apparatus or receiving the object
to be stocked from the exposure apparatus without
10 exposing the objects to be stocked to an external
atmosphere of said first sealing member,
wherein at least one object to be stocked is
stocked in said first sealing member.
- 15 2. The stocker according to claim 1, wherein
the stocker further comprises a load-lock chamber,
and
the object to be stocked is transported to outside
of said first sealing member or received from the
outside of said first sealing member via said load-lock
20 chamber.
3. The stocker according to claim 1, further
comprising atmosphere measurement means for measuring
the internal atmosphere of said first sealing member.
- 25 4. The stocker according to claim 3, wherein said
atmosphere measurement means includes an oxygen analyzer.
5. The stocker according to claim 1, wherein the
first atmosphere has an oxygen concentration of not more

than 5 ppm at its steady state.

6. The stocker according to claim 1, wherein the first atmosphere includes an inert gas atmosphere.

7. The stocker according to claim 6, wherein the inert gas atmosphere includes a nitrogen gas atmosphere, a helium gas atmosphere, or a gas mixture atmosphere of nitrogen gas and helium gas.

8. The stocker according to claim 1, further comprising means for storing said at least one object to be stocked, in a second sealing member inside said first sealing member, and

the object to be stocked is transported to the outside of said first sealing member while stored in said second sealing member.

9. The stocker according to claim 1, wherein the stocker is connected to the exposure apparatus via a highly airtight transfer path.

10. The stocker according to claim 1, wherein said atmosphere control means has gas injection means.

11. The stocker according to claim 1, wherein said atmosphere control means has evacuation means.

12. The stocker according to claim 1, wherein the exposure apparatus uses an F₂ excimer laser as an exposure light source.

13. The stocker according to claim 1, further comprising transfer means, arranged in a semiconductor manufacturing line, for transporting the object to be

stocked to manufacturing apparatuses for various processes or receiving the object to be stocked from the manufacturing apparatuses for various processes.

14. The stocker according to claim 1, wherein the
5 object to be stocked includes a reticle or mask.

15. The stocker according to claim 14, further comprising a reticle changer for supplying a desired reticle or mask to the exposure apparatus.

16. The stocker according to claim 1, wherein the
10 object to be stocked includes a wafer.

17. An exposure apparatus comprising a stocker,
said stocker having:

a first sealing member;

15 atmosphere control means for controlling an
internal atmosphere of said first sealing member to a first atmosphere; and

transfer means for transporting an object to be stocked to the exposure apparatus or receiving the object to be stocked from the exposure apparatus without
20 exposing the object to be stocked to an external atmosphere of said first sealing member,

wherein at least one object to be stocked is stocked in said first sealing member.

18. A stocker comprising:

25 a first sealing member;

first atmosphere control means for controlling an internal atmosphere of said first sealing member to a

atmosphere measurement means includes an oxygen analyzer.

22. The stocker according to claim 18, wherein
the first atmosphere has an oxygen concentration
of not more than 50 ppm at its steady state, and

5 the second atmosphere has an oxygen concentration
of not more than 5 ppm at its steady state.

23. The stocker according to claim 18, wherein the first and second atmospheres include an inert gas atmosphere.

24. The stocker according to claim 23, wherein the inert gas atmosphere includes a nitrogen gas atmosphere, a helium gas atmosphere, or a gas mixture atmosphere of nitrogen gas and helium gas.

25. The stocker according to claim 18, wherein the
15 stocker is connected to the exposure apparatus via a
highly airtight transfer path.

26. The stocker according to claim 18, wherein said first and second atmosphere control means have gas injection means.

20 27. The stocker according to claim 18, wherein said
first and second atmosphere control means have
evacuation means.

28. The stocker according to claim 18, wherein the exposure apparatus uses an F₂ excimer laser as an exposure light source.

29. The stocker according to claim 18, further comprising transfer means, arranged in a semiconductor

atmosphere of said first sealing member,

wherein at least one second sealing member which stores said at least one object to be stocked is stocked in said first sealing member.

5 34. A semiconductor device manufacturing method
comprising the steps of:

installing manufacturing apparatuses for various processes including an exposure apparatus in a semiconductor manufacturing factory; and

10 manufacturing a semiconductor device in a
plurality of processes by using the manufacturing
apparatuses,

wherein the exposure apparatus having a stocker,
the stocker having:

15 a first sealing member;

first atmosphere control means for controlling an internal atmosphere of the first sealing member to a first atmosphere;

a second sealing member for storing at least one
20 object to be stocked;

second atmosphere control means for controlling an internal atmosphere of the second sealing member to a second atmosphere; and

transfer means for transporting the object to be
25 stocked to the exposure apparatus or receiving the
object to be stocked from the exposure apparatus while
the object to be stocked is stored in the second sealing

member without being exposed to an external atmosphere
of the first sealing member,

wherein at least one second sealing member which
stores the at least one object to be stocked is stocked
5 in the first sealing member.

35. The method according to claim 34, further
comprising the steps of:

connecting the manufacturing apparatuses by a
local area network; and

10 communicating information about at least one of
the manufacturing apparatuses between the local area
network and an external network of the semiconductor
manufacturing factory.

36. The method according to claim 35, wherein,
15 maintenance information of the manufacturing apparatus
is acquired by data communication by accessing via the
external network a database provided by a vendor or user
of the exposure apparatus, or production is managed by
data communication via the external network with a
20 semiconductor manufacturing factory other than the
semiconductor manufacturing factory.

37. A semiconductor manufacturing factory comprising:
manufacturing apparatuses for various processes
including an exposure apparatus;

25 a local area network for connecting said
manufacturing apparatuses; and

a gateway for allowing the local area network to

